



PFU70R360G / PFD70R360G

N-Channel Super Junction MOSFET

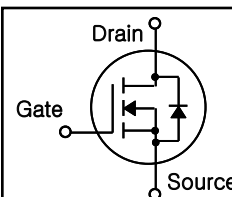
FEATURES

- ❑ New technology for high voltage device
- ❑ Low $R_{DS(on)}$ low conduction losses
- ❑ Small package
- ❑ Ultra low gate charge cause lower driving requirement
- ❑ 100% avalanche tested
- ❑ Halogen Free

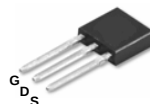
APPLICATION

- ❑ Power Factor Correction(PFC)
- ❑ Switched mode power supply (SMPS)
- ❑ Uninterruptible Power Supply (UPS)

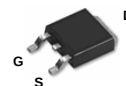
$BV_{DSS} = 700\text{ V}$
 $R_{DS(on)} = 0.36\ \Omega$
 $I_D = 11.0\text{ A}$



I-PAK(TO-251)



D-PAK(TO-252)



Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Value	Units
V_{DS}	Drain-Source Voltage ($V_{GS}=0\text{V}$)	700	V
I_D	Drain Current – Continuous ($T_c = 25^\circ\text{C}$)	11	A
	Drain Current – Continuous ($T_c = 100^\circ\text{C}$)	7.0	A
$I_{DM(pulse)}$	Drain Current – Pulsed * Note 1	33	A
V_{GS}	Gate-Source Voltage ($V_{DS}=0\text{V}$)	± 30	V
E_{AS}	Single Pulsed Avalanche Energy * Note 2	60	mJ
I_{AR}	Avalanche Current * Note 1	5.5	A
E_{AR}	Repetitive Avalanche Energy * Note 1	12	mJ
dv/dt	Drain Source Voltage Slope, $V_{DS} \leq 480\text{V}$	50	V/ns
	Reverse Diode dv/dt, $V_{DS} \leq 480\text{V}$	15	V/ns
P_D	Maximum Power Dissipation ($T_c = 25^\circ\text{C}$)	121	W
	Derate above 25°C	0.97	W/ $^\circ\text{C}$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$

* Limited by maximum junction temperature

Thermal Resistance Characteristics

Symbol	Parameter	Value	Units
$R_{\theta JC}$	Junction-to-Case (Maximum)	1.03	$^\circ\text{C/W}$
$R_{\theta JA}$	Junction-to-Ambient (Maximum)	62	

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Electrical Characteristics $T_A=25\text{ }^{\circ}\text{C}$ unless otherwise specified

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250 uA	2.5	3.0	4.5	V
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 7.0 A	--	360	400	m.ohm
Off Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _D = 250 uA	700	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 700 V, V _{GS} = 0 V	--	--	1	uA
		V _{DS} = 560 V, T _C =125 °C	--	--	100	uA
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V	--	--	100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V	--	--	-100	nA
Dynamic Characteristics						
g _{FS}	Forward Transconductance	V _{DS} = 20V, I _D = 7.0A	--	8	--	S
R _G	Intrinsic Gate Resistance	f = 1.0 MHz, open drain	--	2	--	ohm
C _{iss}	Input Capacitance	V _{DS} = 50 V, V _{GS} = 0 V, f = 1.0 MHz	--	950	--	pF
C _{oss}	Output Capacitance		--	75	--	pF
C _{rss}	Reverse Transfer Capacitance		--	5	--	pF
Q _g	Total Gate Charge	V _{DS} = 560 V, I _D = 11.0 A, V _{GS} = 10 V	--	24	36	nC
Q _{gs}	Gate-Source Charge		--	6	--	nC
Q _{gd}	Gate-Drain Charge		--	8.5	--	nC
Switching Characteristics						
t _{d(on)}	Turn-On Time	V _{DS} = 380 V, I _D = 5.5 A, R _G = 6.8 Ω, V _{GS} = 10V	--	9	--	ns
t _r	Turn-On Rise Time		--	4	--	ns
t _{d(off)}	Turn-Off Delay Time		--	40	60	ns
t _f	Turn-Off Fall Time		--	4.5	7	ns
Source-Drain Diode Maximum Ratings and Characteristics						
I _S	Continuous Source-Drain Diode Forward Current		--	--	11	A
I _{SM}	Pulsed Source-Drain Diode Forward Current		--	--	33	
V _{SD}	Source-Drain Diode Forward Voltage	I _S = 11.0 A, V _{GS} = 0 V	--	0.9	1.2	V
t _{rr}	Reverse Recovery Time	I _S = 11.0 A	--	245	--	ns
Q _{rr}	Reverse Recovery Charge	di/dt = 100 A/μs	--	2.4	--	μC

Notes ;

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2. $V_{DD}=50\text{ V}, R_G=25\text{ }\Omega$, Starting $T_J=25\text{ }^{\circ}\text{C}$

Typical Characteristics

Figure1. On Region Characteristics

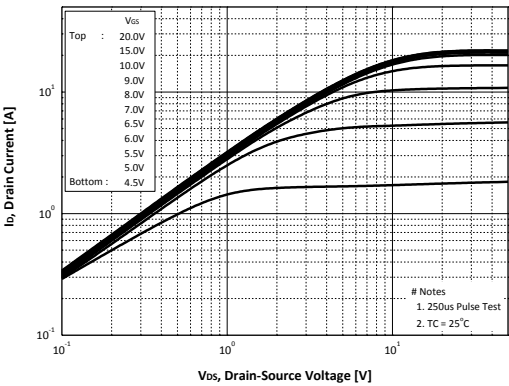


Figure 2. Transfer Characteristics

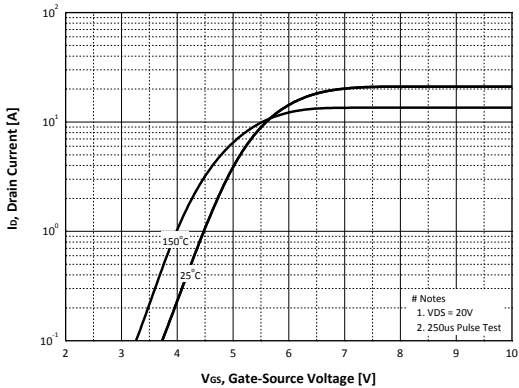


Figure 3. Static Drain-Source On Resistance

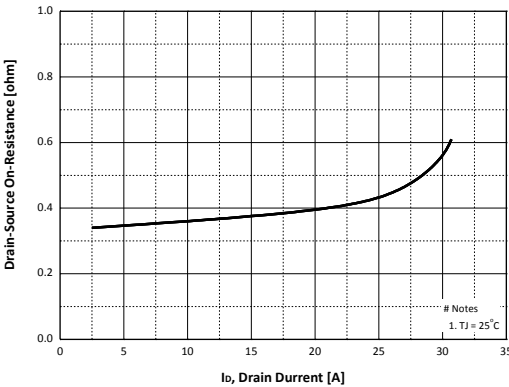


Figure 4. Body Diode Forward Voltage

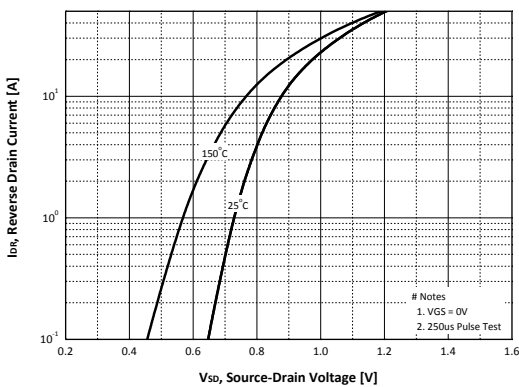


Figure 5. Capacitance Characteristics

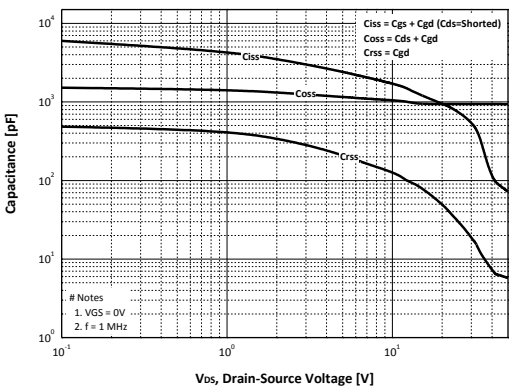
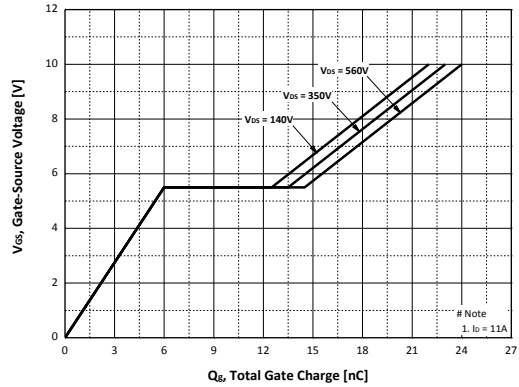


Figure 6. Gate Charge Characteristics



Typical Characteristics (continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

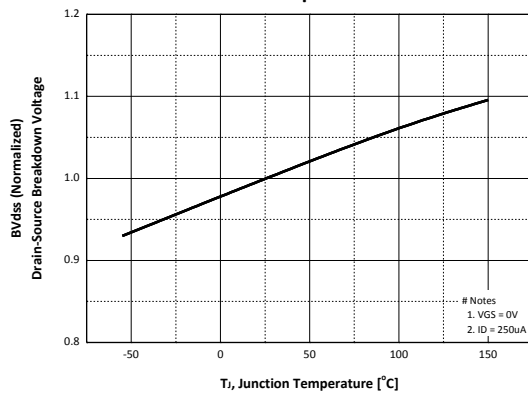


Figure 8. On-Resistance Variation vs. Temperature

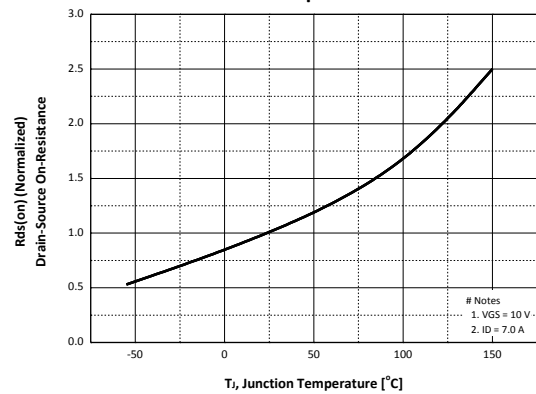


Figure 9. Safe Operation Area

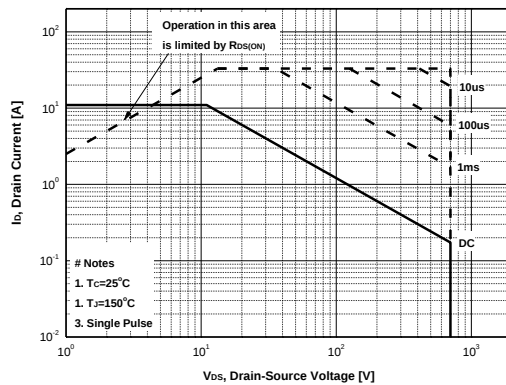


Figure 10. Maximum Drain Current vs. Case Temperature

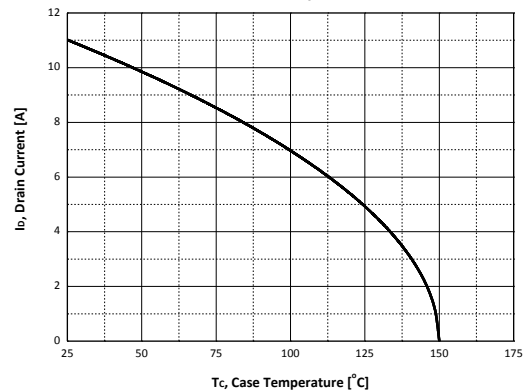
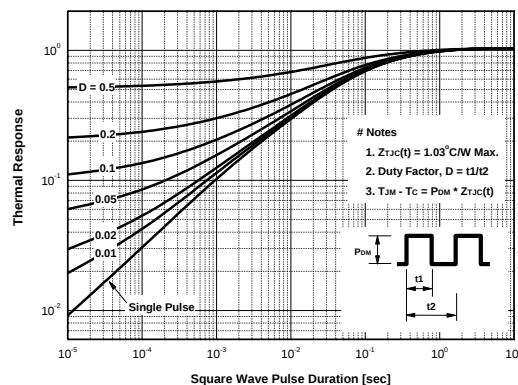
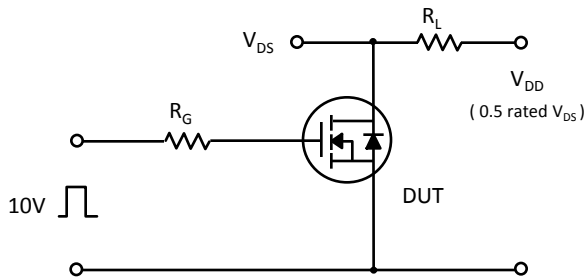


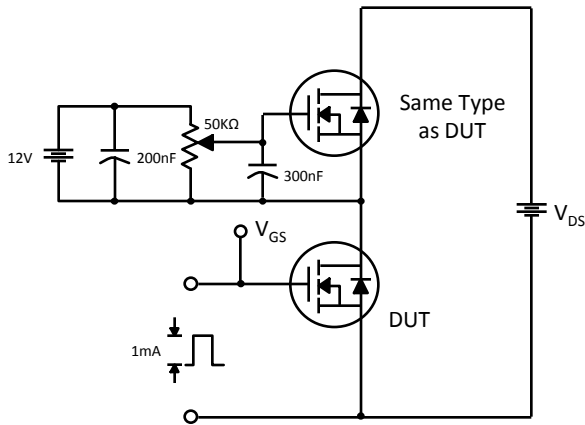
Figure 11. Transient Thermal Response Curve



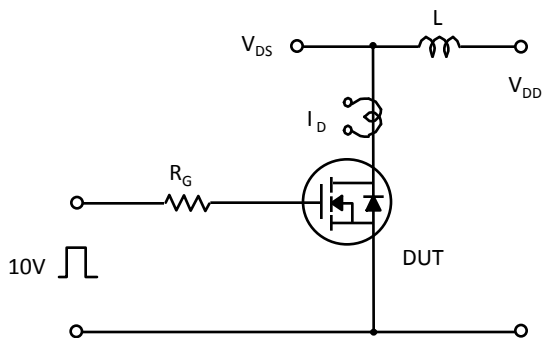
Characteristics Test Circuit & Waveform



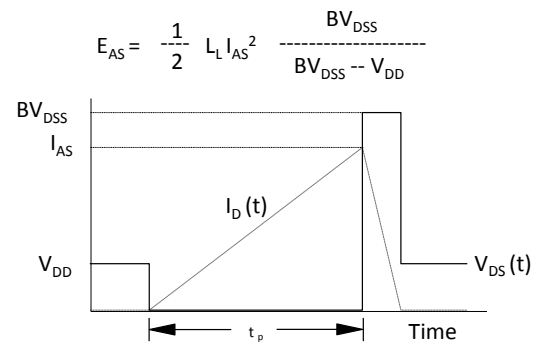
Switching Time Test Circuit & Waveforms



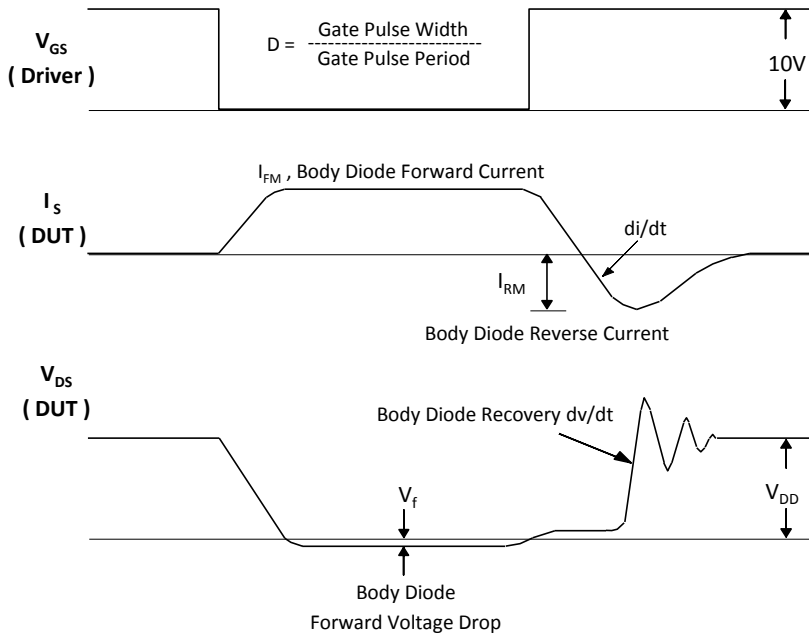
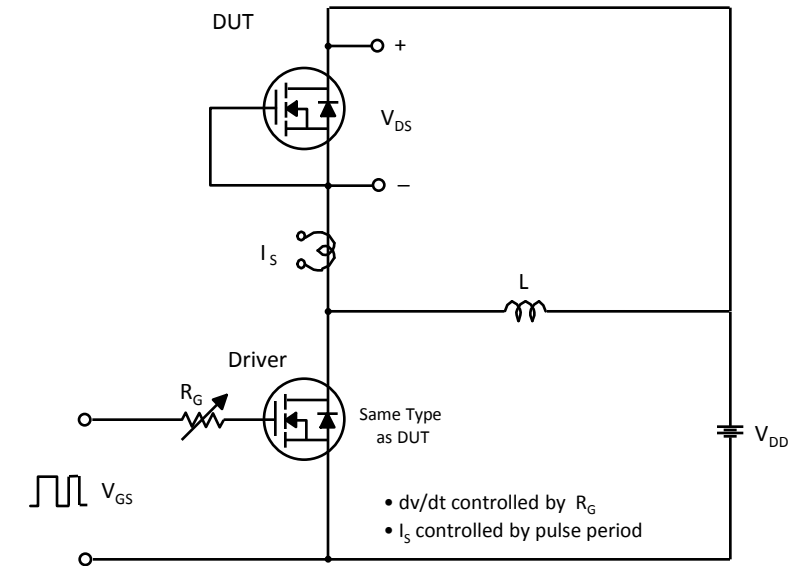
Gate Charge Test Circuit & Waveform



Unclamped Inductive Switching Test Circuit & Waveforms



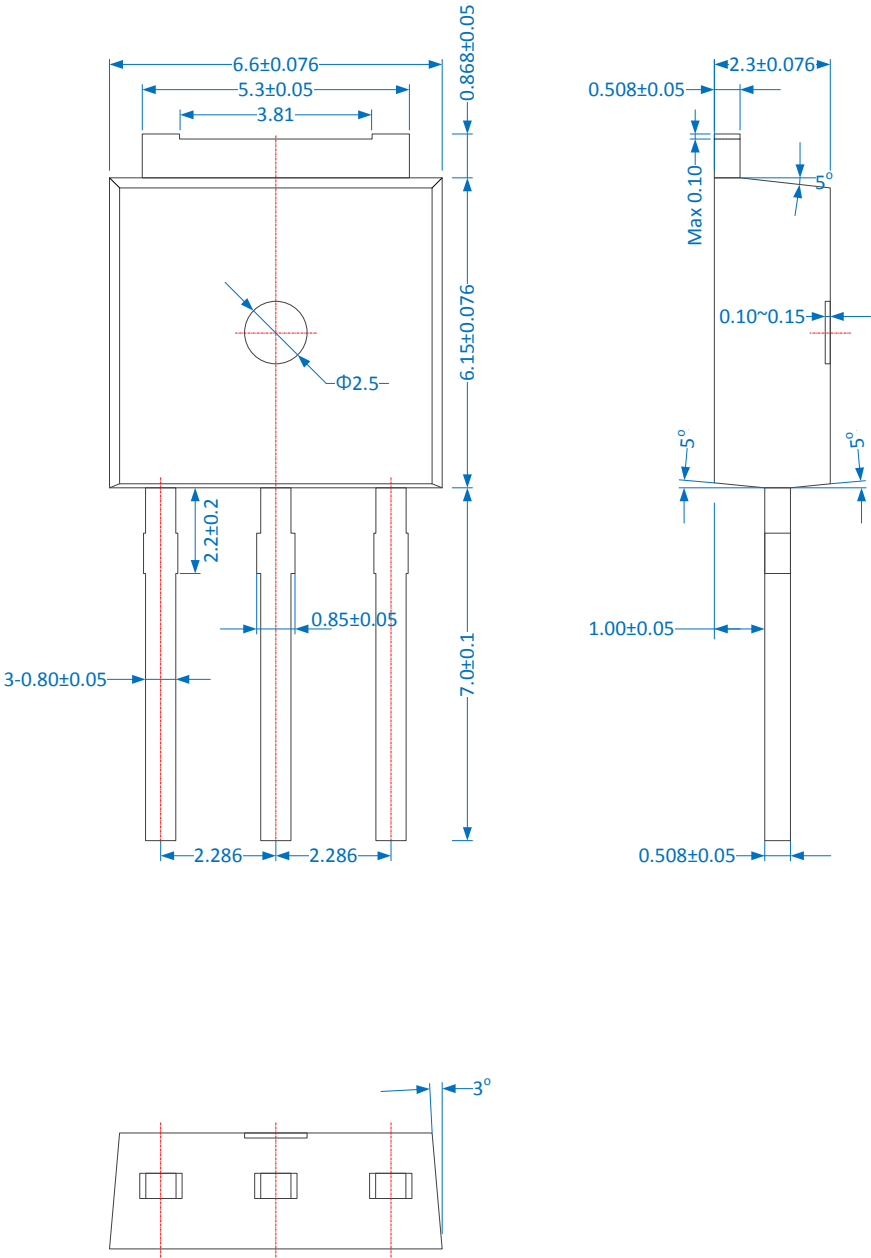
Characteristics Test Circuit & Waveform (continued)



Peak Diode Recovery dv/dt Test Circuit & Waveforms

Package Dimension

I-PAK(TO-251)



Package Dimension

D-PAK(TO-252)

